

SFI Test Report TLK10232

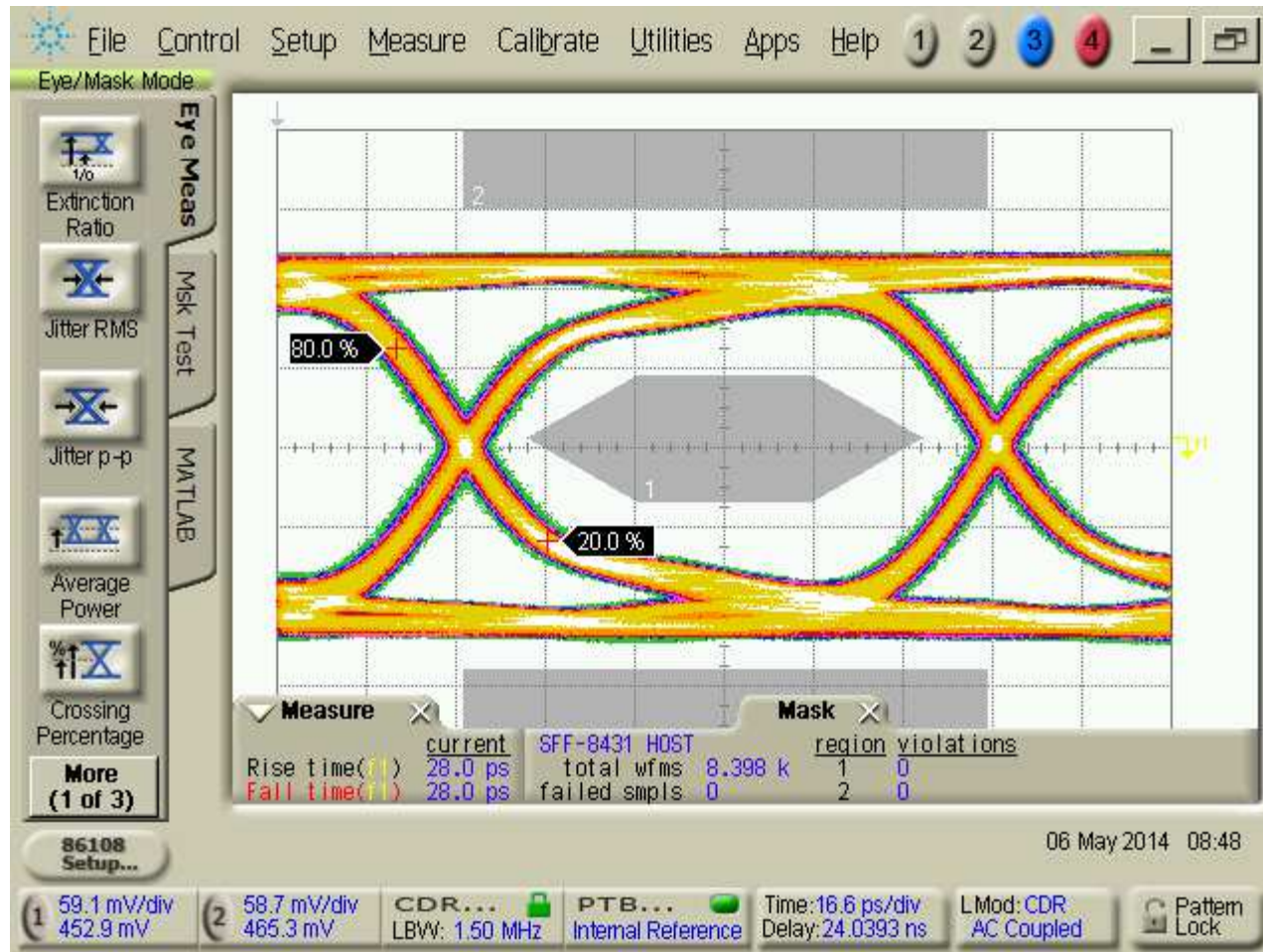
**Communication Interface – CIF
May 2014**

Transmitter Performance Report

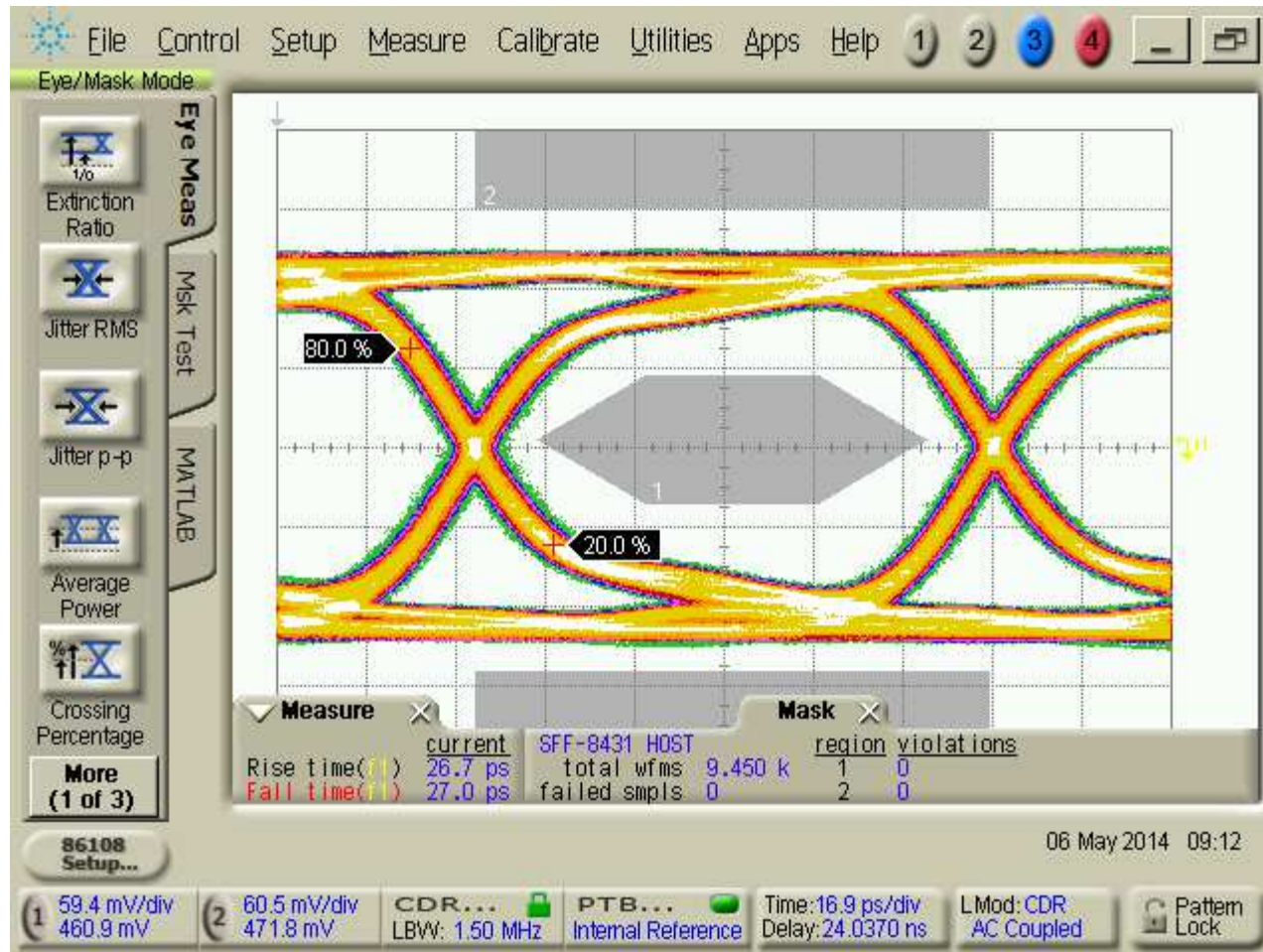
Test Setup

- TLK10232 is configured to supply a compliant SFI eye.
 - Data Rate: 10.3125Gbps
 - Output Swing: 660mV
 - Test Pattern: Valid 64/66B Traffic
- Eye mask used for this test is compliant the SFF-8431 standard (Rev 4.1).
 - Eye Mask Specification used during testing is Host Transmitter Output at compliance point B.

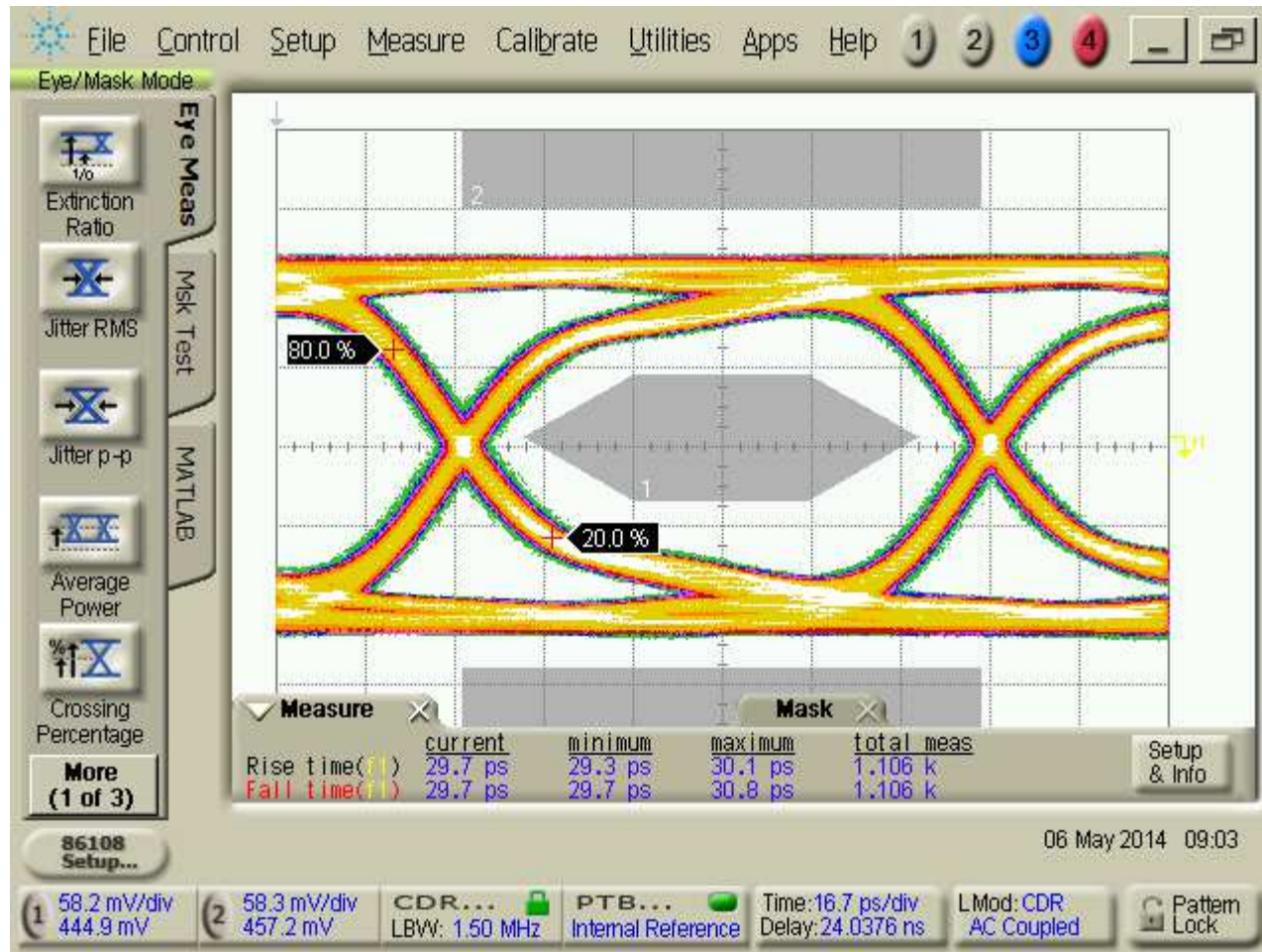
Transmitter Output Eye Diagram @ 25°C



Transmitter Output Eye Diagram @ 85°C

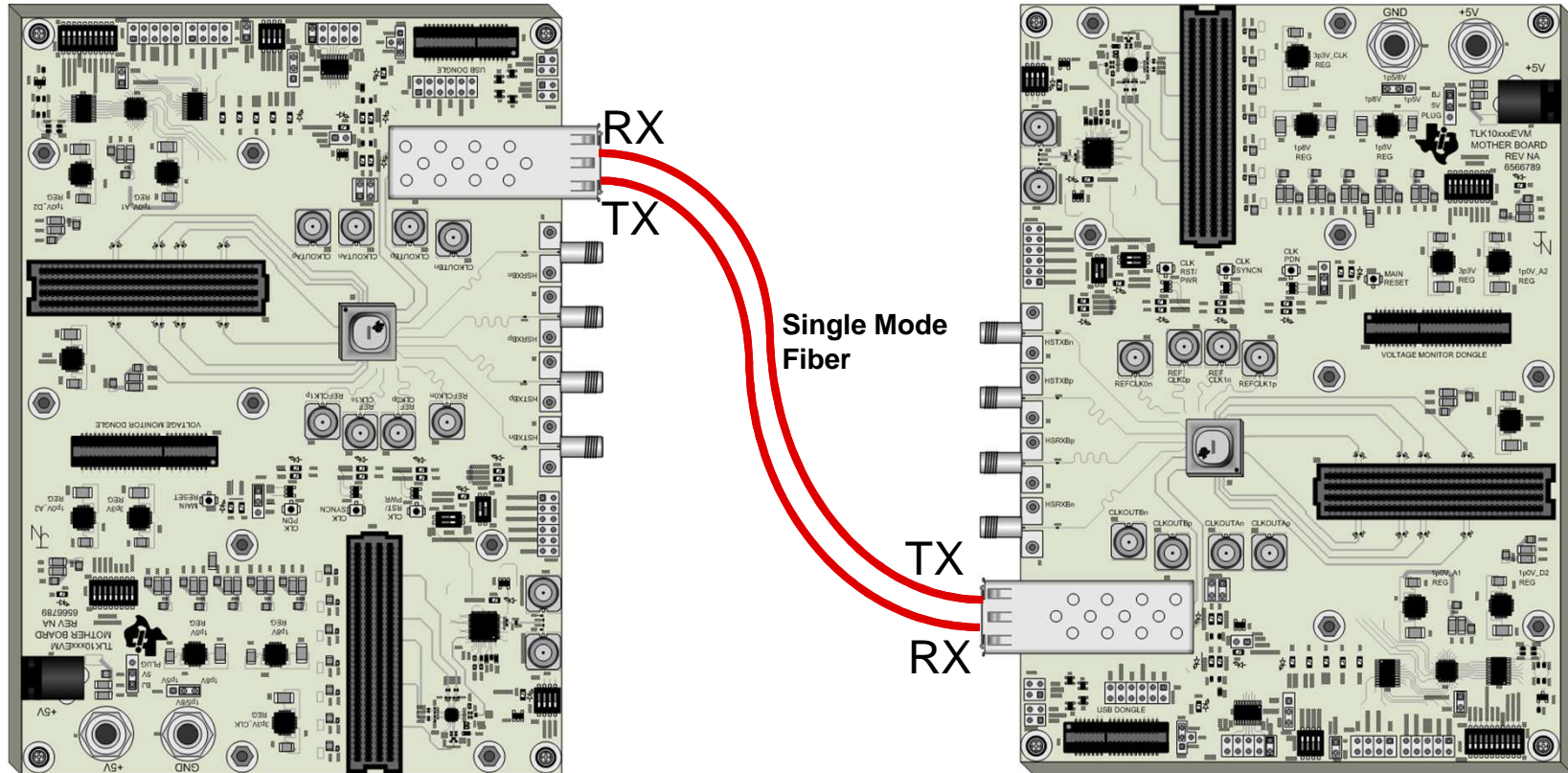


Transmitter Output Eye Diagram @ -40°C



Optical Module Interoperability Report

Test Setup



Test Board A

Test Board B

Interoperability Testing Results

Optical Module A	Optical Module B	BER Achieved	Data Rate
Finisar (1310nm)	Finisar (1310nm)	3×10^{-12}	10.3125Gbps
Finisar (1310nm)	Avago (1310nm)	3×10^{-12}	10.3125Gbps
Finisar (1310nm)	JDSU (1310nm)	3×10^{-12}	10.3125Gbps
Avago (1310nm)	JDSU (1310nm)	3×10^{-12}	10.3125Gbps
JDSU (1310nm)	JDSU (1310nm)	3×10^{-12}	10.3125Gbps
Avago (1310nm)	Avago (1310nm)	3×10^{-12}	10.3125Gbps



For Further Information Contact:

Texas Instruments

CIF – Communication Interface

http://e2e.ti.com/support/interface/high_speed_interface/default.aspx

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